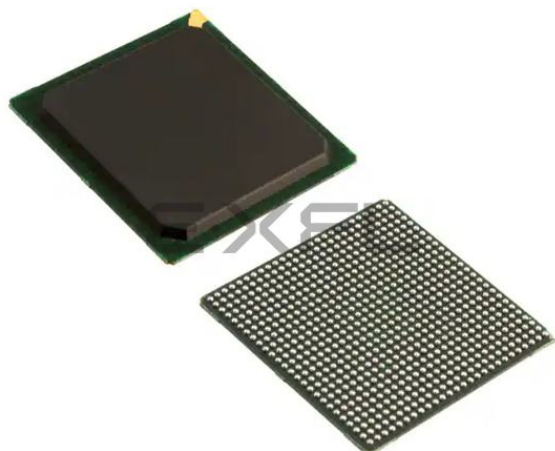




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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Active
Number of LABs/CLBs	8064
Number of Logic Elements/Cells	-
Total RAM Bits	73728
Number of I/O	336
Number of Gates	500000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 85°C (TA)
Package / Case	676-BGA
Supplier Device Package	676-FBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/ax500-2fg676i

Figure 1-8 • AX Routing Structures

Global Resources

Each family member has three types of global signals available to the designer: HCLK, CLK, and GCLR/GPSET. There are four hardwired clocks (HCLK) per device that can directly drive the clock input of each R-cell. Each of the four routed clocks (CLK) can drive the clock, clear, preset, or enable pin of an R-cell or any input of a C-cell (Figure 1-3 on page 1-2).

Global clear (GCLR) and global preset (GPSET) drive the clear and preset inputs of each R-cell as well as each I/O Register on a chip-wide basis at power-up.

Each HCLK and CLK has an associated analog PLL (a total of eight per chip). Each embedded PLL can be used for clock delay minimization, clock delay adjustment, or clock frequency synthesis. The PLL is capable of operating with input frequencies ranging from 14 MHz to 200 MHz and can generate output frequencies between 20 MHz and 1 GHz. The clock can be either divided or multiplied by factors ranging from 1 to 64. Additionally, multiply and divide settings can be used in any combination as long as the resulting clock frequency is between 20 MHz and 1 GHz. Adjacent PLLs can be cascaded to create complex frequency combinations.

The PLL can be used to introduce either a positive or a negative clock delay of up to 3.75 ns in 250 ps increments. The reference clock required to drive the PLL can be derived from three sources: external input pad (either single-ended or differential), internal logic, or the output of an adjacent PLL.

Low Power (LP) Mode

The AX architecture was created for high-performance designs but also includes a low power mode (activated via the LP pin). When the low power mode is activated, I/O banks can be disabled (inputs disabled, outputs tristated), and PLLs can be placed in a power-down mode. All internal register states are maintained in this mode. Furthermore, individual I/O banks can be configured to opt out of the LP mode, thereby giving the designer access to critical signals while the rest of the chip is in low power mode.

The power can be further reduced by providing an external voltage source (V_{PUMP}) to the device to bypass the internal charge pump (See "Low Power Mode" on page 2-106 for more information).

Table 2-5 • Different Components Contributing to the Total Power Consumption in Axcelerator Devices

Component	Definition	Device Specific Value (in $\mu\text{W}/\text{MHz}$)				
		AX125	AX250	AX500	AX1000	AX2000
P1	Core tile HCLK power component	33	49	71	130	216
P2	R-cell power component	0.2	0.2	0.2	0.2	0.2
P3	HCLK signal power dissipation	4.5	4.5	9	13.5	18
P4	Core tile RCLK power component	33	49	71	130	216
P5	R-cell power component	0.3	0.3	0.3	0.3	0.3
P6	RCLK signal power dissipation	6.5	6.5	13	19.5	26
P7	Power dissipation due to the switching activity on the R-cell	1.6	1.6	1.6	1.6	1.6
P8	Power dissipation due to the switching activity on the C-cell	1.4	1.4	1.4	1.4	1.4
P9	Power component associated with the input voltage	10	10	10	10	10
P10	Power component associated with the output voltage	See table Per pin contribution				
P11	Power component associated with the read operation in the RAM block	25	25	25	25	25
P12	Power component associated with the write operation in the RAM block	30	30	30	30	30
P13	Core PLL power component	1.5	1.5	1.5	1.5	1.5

$$P_{total} = P_{dc} + P_{ac}$$

$$P_{dc} = ICCA * VCCA$$

$$P_{ac} = P_{HCLK} + P_{CLK} + P_{R-cells} + P_{C-cells} + P_{inputs} + P_{outputs} + P_{memory} + P_{PLL}$$

$$P_{HCLK} = (P1 + P2 * s + P3 * \sqrt{s}) * F_s$$

s = the number of R-cells clocked by this clock

F_s = the clock frequency

$$P_{CLK} = (P4 + P5 * s + P6 * \sqrt{s}) * F_s$$

s = the number of R-cells clocked by this clock

F_s = the clock frequency

$$P_{R-cells} = P7 * ms * F_s$$

ms = the number of R-cells switching at each F_s cycle

F_s = the clock frequency

$$P_{C-cells} = P8 * mc * F_s$$

mc = the number of C-cells switching at each F_s cycle

F_s = the clock frequency

$$P_{inputs} = P9 * pi * F_{pi}$$

pi = the number of inputs

F_{pi} = the average input frequency

User-Defined Supply Pins

VREF Supply Voltage

Reference voltage for I/O banks. VREF pins are configured by the user from regular I/O pins; VREF pins are not in fixed locations. There can be one or more VREF pins in an I/O bank.

Global Pins

HCLKA/B/C/D Dedicated (Hardwired) Clocks A, B, C and D

These pins are the clock inputs for sequential modules or north PLLs. Input levels are compatible with all supported I/O standards. There is a P/N pin pair for support of differential I/O standards. Single-ended clock I/Os can only be assigned to the P side of a paired I/O. This input is directly wired to each R-cell and offers clock speeds independent of the number of R-cells being driven. When the HCLK pins are unused, it is recommended that they are tied to ground.

CLKE/F/G/H Routed Clocks E, F, G, and H

These pins are clock inputs for clock distribution networks or south PLLs. Input levels are compatible with all supported I/O standards. There is a P/N pin pair for support of differential I/O standards. Single-ended clock I/Os can only be assigned to the P side of a paired I/O. The clock input is buffered prior to clocking the R-cells. When the CLK pins are unused, Microsemi recommends that they are tied to ground.

JTAG/Probe Pins

PRA/B/C/D Probe A, B, C and D

The Probe pins are used to output data from any user-defined design node within the device (controlled with Silicon Explorer II). These independent diagnostic pins can be used to allow real-time diagnostic output of any signal path within the device. The pins' probe capabilities can be permanently disabled to protect programmed design confidentiality. The probe pins are of LVTTTL output levels.

TCK Test Clock

Test clock input for JTAG boundary-scan testing and diagnostic probe (Silicon Explorer II).

TDI Test Data Input

Serial input for JTAG boundary-scan testing and diagnostic probe. TDI is equipped with an internal 10 k Ω pull-up resistor.

TDO Test Data Output

Serial output for JTAG boundary-scan testing.

TMS Test Mode Select

The TMS pin controls the use of the IEEE 1149.1 boundary-scan pins (TCK, TDI, TDO, TRST). TMS is equipped with an internal 10 k Ω pull-up resistor.

TRST Boundary Scan Reset Pin

The TRST pin functions as an active-low input to asynchronously initialize or reset the boundary scan circuit. The TRST pin is equipped with a 10 k Ω pull-up resistor.

Special Functions

LP Low Power Pin

The LP pin controls the low power mode of Axcelerator devices. The device is placed in the low power mode by connecting the LP pin to logic high. To exit the low power mode, the LP pin must be set Low. Additionally, the LP pin must be set Low during chip powering-up or chip powering-down operations. See "Low Power Mode" on page 2-106 for more details.

NC No Connection

This pin is not connected to circuitry within the device. These pins can be driven to any voltage or can be left floating with no effect on the operation of the device.

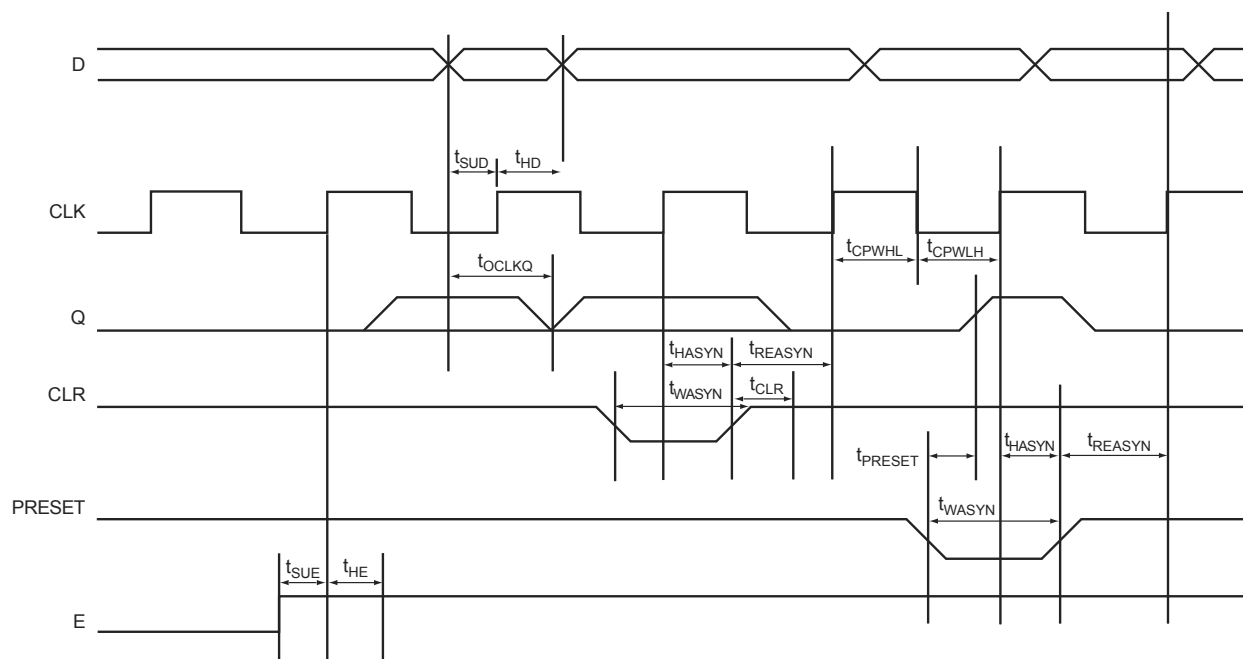


Figure 2-13 • Output Register Timing Characteristics

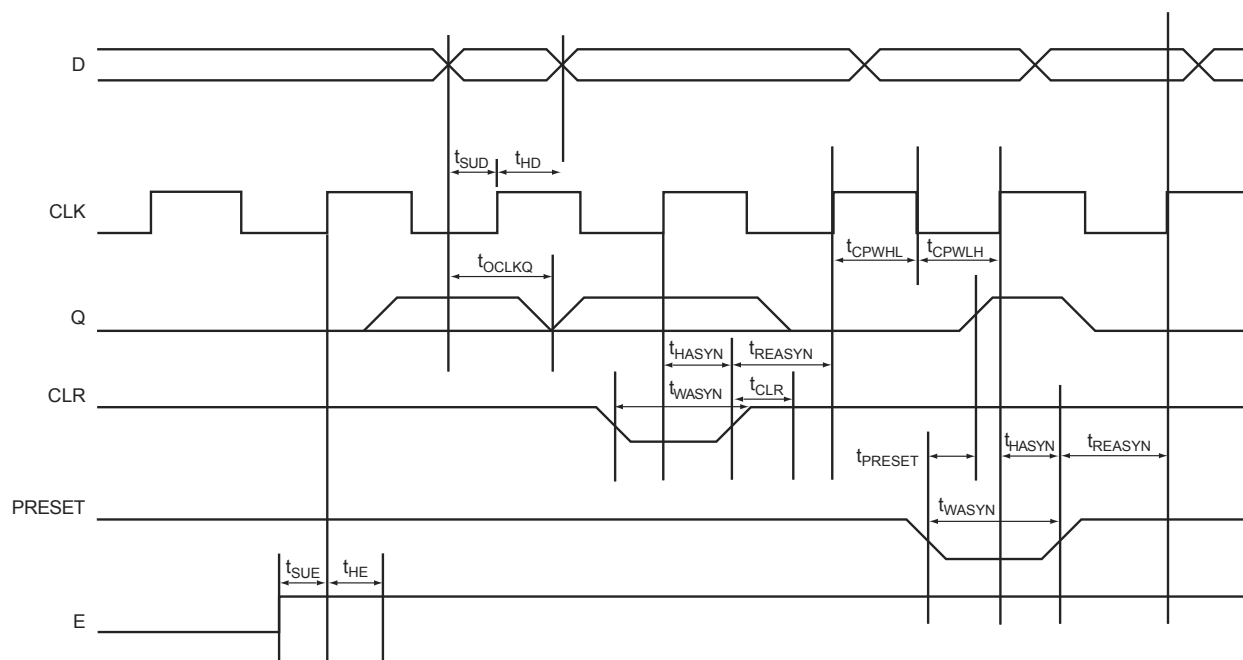


Figure 2-14 • Output Enable Register Timing Characteristics

Timing Characteristics

Table 2-32 • 1.5V LVCMOS I/O Module

Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 1.4 V, TJ = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	Units
LVCMOS15 (JESD8-11) I/O Module Timing								
t _{DP}	Input Buffer		3.59		4.09		4.81	ns
t _{PY}	Output Buffer		6.05		6.89		8.10	ns
t _{ENZL}	Enable to Pad Delay through the Output Buffer—Z to Low		3.31		3.34		3.34	ns
t _{ENZH}	Enable to Pad Delay through the Output Buffer—Z to High		4.56		4.58		4.59	ns
t _{ENLZ}	Enable to Pad Delay through the Output Buffer—Low to Z		6.37		7.25		8.52	ns
t _{ENHZ}	Enable to Pad Delay through the Output Buffer—High to Z		6.94		7.90		9.29	ns
t _{IOCLKQ}	Sequential Clock-to-Q for the I/O Input Register		0.67		0.77		0.90	ns
t _{IOCLKY}	Clock-to-output Y for the I/O Output Register and the I/O Enable Register		0.67		0.77		0.90	ns
t _{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t _{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t _{HD}	Data Input Hold		0.00		0.00		0.00	ns
t _{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t _{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t _{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t _{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t _{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t _{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t _{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t _{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

Timing Characteristics

Table 2-61 • LVPECL I/O Module

Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	Units
LVPECL Output Module Timing								
t _{DP}	Input Buffer		1.66		1.89		2.22	ns
t _{PY}	Output Buffer		2.24		2.55		3.00	ns
t _{CLKQ}	Clock-to-Q for the I/O input register		0.67		0.77		0.90	ns
t _{OCLKQ}	Clock-to-Q for the IO output register and the I/O enable register		0.67		0.77		0.90	ns
t _{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t _{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t _{HD}	Data Input Hold		0.00		0.00		0.00	ns
t _{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t _{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t _{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t _{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t _{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t _{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t _{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t _{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

Embedded Memory

The AX architecture provides extensive, high-speed memory resources to the user. Each 4,608 bit block of RAM contains its own embedded FIFO controller, allowing the user to configure each block as either RAM or FIFO.

To meet the needs of high performance designs, the memory blocks operate in synchronous mode for both read and write operations. However, the read and write clocks are completely independent, and each may operate up to and above 500 MHz.

No additional core logic resources are required to cascade the address and data buses when cascading different RAM blocks. Dedicated routing runs along each column of RAM to facilitate cascading.

The AX memory block includes dedicated FIFO control logic to generate internal addresses and external flag logic (FULL, EMPTY, AFULL, AEMPTY). Since read and write operations can occur asynchronously to one another, special control circuitry is included to prevent metastability, overflow, and underflow. A block diagram of the memory module is illustrated in Figure 2-57.

During RAM operation, read (RA) and write (WA) addresses are sourced by user logic and the FIFO controller is ignored. In FIFO mode, the internal addresses are generated by the FIFO controller and routed to the RAM array by internal MUXes. Enables with programmable polarity are provided to create upper address bits for cascading up to 16 memory blocks. When cascading memory blocks, the bussed signals WA, WD, WEN, RA, RD, and REN are internally linked to eliminate external routing congestion.

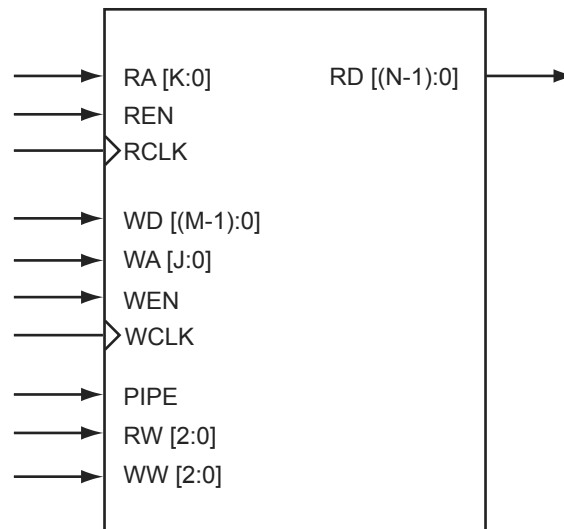


Figure 2-57 • Axcelerator Memory Module

Timing Characteristics

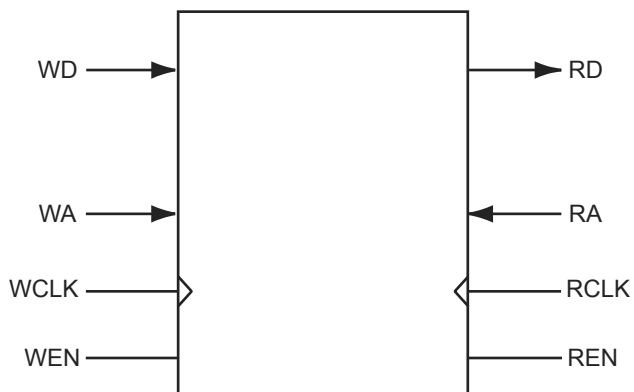


Figure 2-58 • SRAM Model

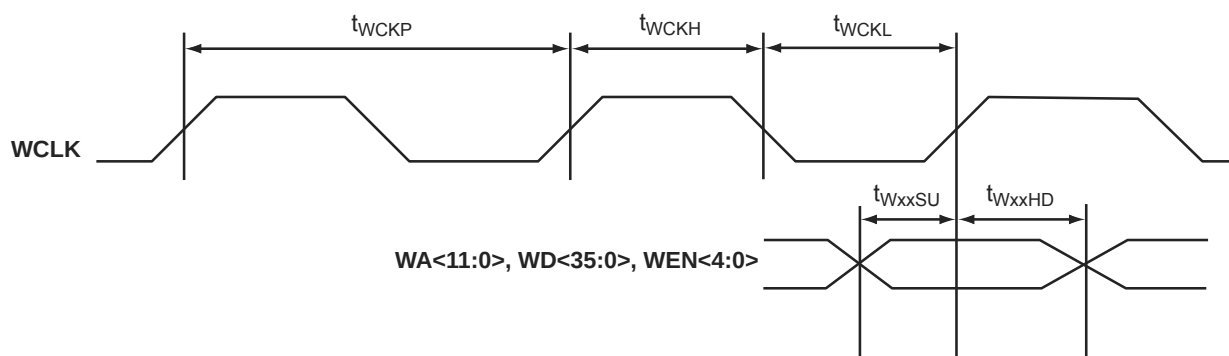


Figure 2-59 • RAM Write Timing Waveforms

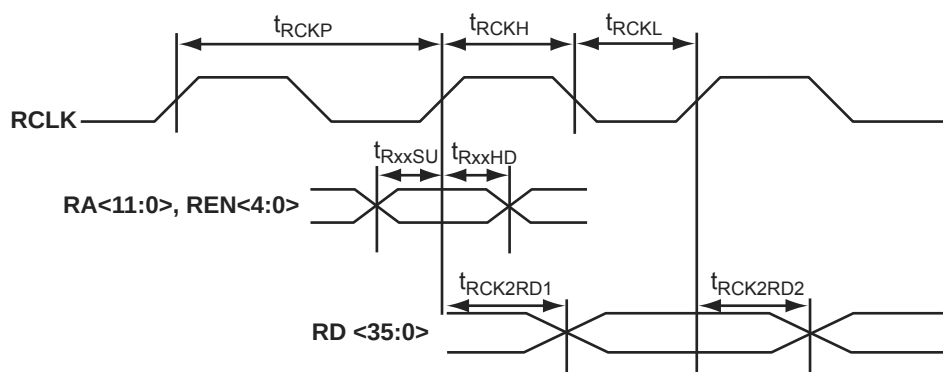


Figure 2-60 • RAM Read Timing Waveforms

Table 2-98 • One FIFO Block

Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		Units
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	
FIFO Module Timing								
t _{WSU}	Write Setup		11.40		12.98		15.26	ns
t _{WHD}	Write Hold		0.22		0.25		0.30	ns
t _{WCKH}	WCLK High		0.75		0.75		0.75	ns
t _{WCKL}	WCLK Low		0.88		0.88		0.88	ns
t _{WCKP}	Minimum WCLK Period	1.63		1.63		1.63		ns
t _{RSU}	Read Setup		11.63		13.25		15.58	ns
t _{RHD}	Read Hold		0.00		0.00		0.00	ns
t _{RCKH}	RCLK High		0.77		0.77		0.77	ns
t _{RCKL}	RCLK Low		0.93		0.93		0.93	ns
t _{RCKP}	Minimum RCLK period	1.70		1.70		1.70		ns
t _{CLRHF}	Clear High		0.00		0.00		0.00	ns
t _{CLR2FF}	Clear-to-flag (EMPTY/FULL)		1.92		2.18		2.57	ns
t _{CLR2AF}	Clear-to-flag (AEMPTY/AFULL)		4.39		5.00		5.88	ns
t _{CK2FF}	Clock-to-flag (EMPTY/FULL)		2.13		2.42		2.85	ns
t _{CK2AF}	Clock-to-flag (AEMPTY/AFULL)		5.04		5.75		6.75	ns
t _{RCK2RD1}	RCLK-To-OUT (Pipelined)		1.32		1.51		1.77	ns
t _{RCK2RD2}	RCLK-To-OUT (Non-Pipelined)		2.16		2.46		2.90	ns

Note: Timing data for this single block FIFO has a depth of 4,096. For all other combinations, use Microsemi's timing software.

FG256	
AX250 Function	Pin Number
VCCA	L9
VCCA	N3
VCCA	P14
VCCPLA	C7
VCCPLB	D6
VCCPLC	A10
VCCPLD	D10
VCCPLE	P10
VCCPLF	N11
VCCPLG	T7
VCCPLH	N7
VCCDA	A11
VCCDA	A2
VCCDA	C13
VCCDA	D9
VCCDA	H1
VCCDA	J15
VCCDA	N14
VCCDA	N8
VCCDA	P4
VCCDA	R11
VCCDA	R5
VCCIB0	E6
VCCIB0	E7
VCCIB0	E8
VCCIB1	E10
VCCIB1	E11
VCCIB1	E9
VCCIB2	F12
VCCIB2	G12
VCCIB2	H12
VCCIB3	J12
VCCIB3	K12
VCCIB3	L12
VCCIB4	M10

FG256	
AX250 Function	Pin Number
VCCIB4	M11
VCCIB4	M9
VCCIB5	M6
VCCIB5	M7
VCCIB5	M8
VCCIB6	J5
VCCIB6	K5
VCCIB6	L5
VCCIB7	F5
VCCIB7	G5
VCCIB7	H5
VCOMPLA	A7
VCOMPLB	D7
VCOMPLC	B9
VCOMPLD	D11
VCOMPLE	T10
VCOMPLF	N10
VCOMPLG	R8
VCOMPLH	N6
VPUMP	A14

FG324	
AX125 Function	Pin Number
VCCIB5	N7
VCCIB5	N8
VCCIB5	N9
VCCIB6	K6
VCCIB6	L6
VCCIB6	M6
VCCIB7	G6
VCCIB7	H6
VCCIB7	J6
VCOMPLA	B8
VCOMPLB	E8
VCOMPLC	C10
VCOMPLD	E12
VCOMPLE	U11
VCOMPLF	P11
VCOMPLG	T9
VCOMPLH	P7
VPUMP	B15

FG676	
AX1000 Function	Pin Number
NC	D13
NC	D14
PRA	E13
PRB	B14
PRC	Y14
PRD	AD14
TCK	E5
TDI	B3
TDO	G6
TMS	D4
TRST	A2
VCCA	AB4
VCCA	AF24
VCCA	C1
VCCA	C26
VCCA	J10
VCCA	J11
VCCA	J12
VCCA	J13
VCCA	J14
VCCA	J15
VCCA	J16
VCCA	J17
VCCA	K18
VCCA	K9
VCCA	L18
VCCA	L9
VCCA	M18
VCCA	M9
VCCA	N18
VCCA	N9
VCCA	P18
VCCA	P9
VCCA	R18
VCCA	R9
VCCA	T18

FG676	
AX1000 Function	Pin Number
VCCA	T9
VCCA	U18
VCCA	U9
VCCA	V10
VCCA	V11
VCCA	V12
VCCA	V13
VCCA	V14
VCCA	V15
VCCA	V16
VCCA	V17
VCCPLA	E12
VCCPLB	F13
VCCPLC	E15
VCCPLD	G14
VCCPLE	AF15
VCCPLF	AA14
VCCPLG	AF12
VCCPLH	AB13
VCCDA	A11
VCCDA	A3
VCCDA	AB22
VCCDA	AB5
VCCDA	AD10
VCCDA	AD11
VCCDA	AD13
VCCDA	AD16
VCCDA	AD17
VCCDA	B1
VCCDA	B11
VCCDA	B17
VCCDA	C16
VCCDA	D24
VCCDA	E14
VCCDA	P2
VCCDA	P23

FG676	
AX1000 Function	Pin Number
VCCIB0	G10
VCCIB0	G8
VCCIB0	G9
VCCIB0	H10
VCCIB0	H11
VCCIB0	H12
VCCIB0	H13
VCCIB0	H9
VCCIB1	G17
VCCIB1	G18
VCCIB1	G19
VCCIB1	H14
VCCIB1	H15
VCCIB1	H16
VCCIB1	H17
VCCIB1	H18
VCCIB2	H20
VCCIB2	J19
VCCIB2	J20
VCCIB2	K19
VCCIB2	K20
VCCIB2	L19
VCCIB2	M19
VCCIB2	N19
VCCIB3	P19
VCCIB3	R19
VCCIB3	T19
VCCIB3	U19
VCCIB3	U20
VCCIB3	V19
VCCIB3	V20
VCCIB3	W20
VCCIB4	W14
VCCIB4	W15
VCCIB4	W16
VCCIB4	W17

FG896	
AX2000 Function	Pin Number
IO245PB5F23	AG8
IO246NB5F23	AD8
IO246PB5F23	AD9
IO247NB5F23	AG7
IO247PB5F23	AH7
IO248NB5F23	AK5
IO249NB5F23	AJ5
IO249PB5F23	AJ6
IO250NB5F23	AC8
IO250PB5F23	AC9
IO251NB5F23	AH6
IO251PB5F23	AG6
IO252NB5F23	AF6
IO252PB5F23	AF7
IO253NB5F23	AG2
IO253PB5F23	AG1
IO254NB5F23	AE7
IO254PB5F23	AE8
IO255NB5F23	AG5
IO255PB5F23	AH5
IO256NB5F23	AJ4
IO256PB5F23	AK4
Bank 6	
IO257NB6F24	AE4
IO257PB6F24	AF4
IO258NB6F24	AB7
IO258PB6F24	AC7
IO259NB6F24	AD5
IO259PB6F24	AE5
IO260NB6F24	AF1
IO260PB6F24	AF2
IO261NB6F24	AF3
IO261PB6F24	AG3
IO262NB6F24	AC4
IO262PB6F24	AD4

FG896	
AX2000 Function	Pin Number
IO263NB6F24	AD3
IO263PB6F24	AE3
IO264NB6F24	AB6
IO264PB6F24	AC6
IO265NB6F24	AD1
IO265PB6F24	AE1
IO266NB6F24	AA8
IO266PB6F24	AB8
IO267NB6F25	AB5
IO267PB6F25	AC5
IO268NB6F25	AB3
IO268PB6F25	AC3
IO269NB6F25	AC2
IO269PB6F25	AD2
IO270NB6F25	Y7
IO270PB6F25	AA7
IO271NB6F25	AA4
IO271PB6F25	AB4
IO272NB6F25	Y6
IO272PB6F25	AA6
IO273NB6F25	AB1*
IO273PB6F25	AE2*
IO274NB6F25	W8
IO274PB6F25	Y8
IO275NB6F25	Y5
IO275PB6F25	AA5
IO277NB6F25	AA2
IO277PB6F25	AA1
IO278NB6F26	W6
IO278PB6F26	W7
IO279NB6F26	Y3
IO279PB6F26	Y4
IO280NB6F26	V8
IO280PB6F26	V9
IO281NB6F26	Y1

FG896	
AX2000 Function	Pin Number
IO281PB6F26	Y2
IO282NB6F26	V5
IO282PB6F26	W5
IO284NB6F26	V7
IO284PB6F26	V6
IO285NB6F26	W3
IO285PB6F26	W4
IO286NB6F26	U8
IO286PB6F26	U9
IO287NB6F26	W1
IO287PB6F26	W2
IO288NB6F26	U7
IO288PB6F26	U6
IO290NB6F27	U4
IO290PB6F27	V4
IO291NB6F27	U3
IO291PB6F27	V3
IO292NB6F27	T5
IO292PB6F27	U5
IO293NB6F27	U2
IO293PB6F27	V2
IO294NB6F27	T8
IO294PB6F27	T9
IO296NB6F27	T1
IO296PB6F27	U1
IO298NB6F27	T7
IO298PB6F27	T6
IO299NB6F27	R2
IO299PB6F27	T2
Bank 7	
IO300NB7F28	R8
IO300PB7F28	R9
IO302NB7F28	R4
IO302PB7F28	R5
IO303NB7F28	P1

CQ352	
AX250 Function	Pin Number
VCCDA	346
VCCIB0	321
VCCIB0	333
VCCIB0	344
VCCIB1	273
VCCIB1	285
VCCIB1	297
VCCIB2	227
VCCIB2	239
VCCIB2	245
VCCIB2	257
VCCIB3	185
VCCIB3	197
VCCIB3	203
VCCIB3	215
VCCIB4	144
VCCIB4	156
VCCIB4	168
VCCIB5	96
VCCIB5	108
VCCIB5	120
VCCIB6	50
VCCIB6	62
VCCIB6	68
VCCIB6	80
VCCIB7	8
VCCIB7	20
VCCIB7	26
VCCIB7	38
VCCPLA	317
VCCPLB	315
VCCPLC	303
VCCPLD	301
VCCPLE	140
VCCPLF	138

CQ352	
AX250 Function	Pin Number
VCCPLG	126
VCCPLH	124
VCOMPLA	318
VCOMPLB	316
VCOMPLC	304
VCOMPLD	302
VCOMPLE	141
VCOMPLF	139
VCOMPLG	127
VCOMPLH	125
VPUMP	267

CQ352		CQ352		CQ352	
AX500 Function	Pin Number	AX500 Function	Pin Number	AX500 Function	Pin Number
GND	21	GND	240	TDI	348
GND	27	GND	246	TDO	347
GND	33	GND	252	TMS	350
GND	39	GND	258	TRST	351
GND	45	GND	264	VCCA	3
GND	51	GND	265	VCCA	14
GND	57	GND	274	VCCA	32
GND	63	GND	280	VCCA	56
GND	69	GND	286	VCCA	74
GND	75	GND	292	VCCA	87
GND	81	GND	298	VCCA	102
GND	88	GND	310	VCCA	114
GND	89	GND	322	VCCA	150
GND	97	GND	330	VCCA	162
GND	103	GND	334	VCCA	175
GND	109	GND	340	VCCA	191
GND	115	GND	345	VCCA	209
GND	121	GND/LP	352	VCCA	233
GND	133	NC	91	VCCA	251
GND	145	NC	117	VCCA	263
GND	151	NC	130	VCCA	279
GND	157	NC	131	VCCA	291
GND	163	NC	148	VCCA	329
GND	169	NC	174	VCCA	339
GND	176	NC	268	VCCDA	2
GND	177	NC	294	VCCDA	44
GND	186	NC	307	VCCDA	90
GND	192	NC	308	VCCDA	116
GND	198	NC	327	VCCDA	132
GND	204	NC	328	VCCDA	149
GND	210	PRA	312	VCCDA	178
GND	216	PRB	311	VCCDA	221
GND	222	PRC	135	VCCDA	266
GND	228	PRD	134	VCCDA	293
GND	234	TCK	349	VCCDA	309

CQ352		CQ352		CQ352	
AX1000 Function	Pin Number	AX1000 Function	Pin Number	AX1000 Function	Pin Number
GND	21	GND	240	VCCA	14
GND	27	GND	246	VCCA	32
GND	33	GND	252	VCCA	56
GND	39	GND	258	VCCA	74
GND	45	GND	264	VCCA	87
GND	51	GND	265	VCCA	102
GND	57	GND	274	VCCA	114
GND	63	GND	280	VCCA	150
GND	69	GND	286	VCCA	162
GND	75	GND	292	VCCA	175
GND	81	GND	298	VCCA	191
GND	88	GND	310	VCCA	209
GND	89	GND	322	VCCA	233
GND	97	GND	330	VCCA	251
GND	103	GND	334	VCCA	263
GND	109	GND	340	VCCA	279
GND	115	GND	345	VCCA	291
GND	121	GND	352	VCCA	329
GND	133	NC	91	VCCA	339
GND	145	NC	130	VCCDA	2
GND	151	NC	131	VCCDA	44
GND	157	NC	174	VCCDA	90
GND	163	NC	268	VCCDA	116
GND	169	NC	307	VCCDA	117
GND	176	NC	308	VCCDA	132
GND	177	PRA	312	VCCDA	148
GND	186	PRB	311	VCCDA	149
GND	192	PRC	135	VCCDA	178
GND	198	PRD	134	VCCDA	221
GND	204	TCK	349	VCCDA	266
GND	210	TDI	348	VCCDA	293
GND	216	TDO	347	VCCDA	294
GND	222	TMS	350	VCCDA	309
GND	228	TRST	351	VCCDA	327
GND	234	VCCA	3	VCCDA	328

CQ352	
AX2000 Function	Pin Number
VCCDA	346
VCCIB0	321
VCCIB0	333
VCCIB0	344
VCCIB1	273
VCCIB1	285
VCCIB1	297
VCCIB2	227
VCCIB2	239
VCCIB2	245
VCCIB2	257
VCCIB3	185
VCCIB3	197
VCCIB3	203
VCCIB3	215
VCCIB4	144
VCCIB4	156
VCCIB4	168
VCCIB5	96
VCCIB5	108
VCCIB5	120
VCCIB6	50
VCCIB6	62
VCCIB6	68
VCCIB6	80
VCCIB7	8
VCCIB7	20
VCCIB7	26
VCCIB7	38
VCCPLA	317
VCCPLB	315
VCCPLC	303
VCCPLD	301
VCCPLE	140
VCCPLF	138

CQ352	
AX2000 Function	Pin Number
VCCPLG	126
VCCPLH	124
VCOMPLA	318
VCOMPLB	316
VCOMPLC	304
VCOMPLD	302
VCOMPLE	141
VCOMPLF	139
VCOMPLG	127
VCOMPLH	125
VPUMP	267

CG624		CG624		CG624	
AX1000 Function	Pin Number	AX1000 Function	Pin Number	AX1000 Function	Pin Number
IO63PB1F5	G18	IO84NB2F7	M20	IO105NB3F9	R23
Bank 2		IO84PB2F7	M21	IO105PB3F9	P23
IO64NB2F6	M17	IO86NB2F8	E25	IO106NB3F9	R19
IO64PB2F6	G22	IO86PB2F8	D25	IO106PB3F9	R20
IO65NB2F6	J21	IO87NB2F8	L24	IO107NB3F10	AB24
IO65PB2F6	J20	IO87PB2F8	K24	IO108NB3F10	R25
IO66NB2F6	L23	IO88NB2F8	G24	IO108PB3F10	P25
IO66PB2F6	K20	IO88PB2F8	F24	IO109NB3F10	U25
IO67NB2F6	F23	IO89NB2F8	J25	IO109PB3F10	T25
IO67PB2F6	E23	IO90NB2F8	G25	IO110NB3F10	U24
IO68NB2F6	L18	IO90PB2F8	F25	IO110PB3F10	U23
IO68PB2F6	K18	IO91NB2F8	L25	IO112NB3F10	T24
IO70NB2F6	E24	IO91PB2F8	K25	IO112PB3F10	R24
IO70PB2F6	D24	IO92NB2F8	J24	IO113NB3F10	Y25
IO71NB2F6	H23	IO92PB2F8	H24	IO113PB3F10	W25
IO71PB2F6	G23	IO93PB2F8	J23	IO114NB3F10	V23
IO72NB2F6	L19	IO94NB2F8	N24	IO114PB3F10	V24
IO72PB2F6	K19	IO94PB2F8	M24	IO116NB3F10	AA24
IO74NB2F7	J22	IO95NB2F8	N25	IO116PB3F10	Y24
IO74PB2F7	H22	IO95PB2F8	M25	IO117NB3F10	AB25
IO75NB2F7	N23	Bank 3		IO117PB3F10	AA25
IO75PB2F7	M23	IO96NB3F9	T18	IO118NB3F11	T20
IO76NB2F7	N17	IO96PB3F9	R18	IO118PB3F11	R21
IO76PB2F7	N16	IO97NB3F9	N20	IO120NB3F11	W22
IO77NB2F7	L22	IO97PB3F9	P24	IO120PB3F11	W23
IO77PB2F7	K22	IO98NB3F9	P20	IO122NB3F11	V22
IO78NB2F7	M19	IO98PB3F9	P19	IO122PB3F11	U22
IO78PB2F7	M18	IO99NB3F9	P21	IO124NB3F11	Y23
IO79NB2F7	N19	IO100NB3F9	T22	IO124PB3F11	AA23
IO79PB2F7	N18	IO100PB3F9	W24	IO126NB3F11	V21
IO80NB2F7	L21	IO101NB3F9	R22	IO126PB3F11	U21
IO80PB2F7	L20	IO101PB3F9	P22	IO128NB3F11	Y22
IO82NB2F7	P18	IO102NB3F9	U19	IO128PB3F11	Y21
IO82PB2F7	P17	IO102PB3F9	T19	Bank 4	
IO83NB2F7	N22	IO104NB3F9	V20	IO129NB4F12	W20
IO83PB2F7	M22	IO104PB3F9	U20	IO129PB4F12	Y20

CG624		CG624		CG624	
AX1000 Function	Pin Number	AX1000 Function	Pin Number	AX1000 Function	Pin Number
IO194NB6F18	Y3	IO215PB6F20	V4	IO237NB7F22	N8
IO194PB6F18	AA3	IO216NB6F20	P8	IO237PB7F22	N7
IO195NB6F18	V6	IO216PB6F20	R3	IO238NB7F22	M5
IO195PB6F18	W4	IO217NB6F20	P7	IO239NB7F22	L6
IO197NB6F18	R5	IO217PB6F20	R7	IO239PB7F22	L5
IO197PB6F18	U3	IO219NB6F20	R4	IO240NB7F22	M4
IO198NB6F18	P6	IO219PB6F20	T4	IO241NB7F22	L7
IO199NB6F18	Y5	IO220NB6F20	P2	IO241PB7F22	M7
IO199PB6F18	W5	IO220PB6F20	R2	IO242NB7F22	J3
IO200NB6F18	V3	IO221NB6F20	N4	IO243NB7F22	M9
IO200PB6F18	W3	IO221PB6F20	P4	IO243PB7F22	M8
IO201NB6F18	T7	IO223NB6F20	M2	IO244NB7F22	P9
IO201PB6F18	U7	IO223PB6F20	N2	IO244PB7F22	N6
IO202NB6F18	V2	IO224NB6F20	N3	IO245NB7F22	K8
IO203NB6F19	W2	IO224PB6F20	P3	IO245PB7F22	L8
IO203PB6F19	Y2	Bank 7		IO246NB7F22	F3
IO204NB6F19	AA1	IO225NB7F21	J2	IO246PB7F22	E3
IO204PB6F19	AB1	IO225PB7F21	J1	IO247NB7F23	K7
IO205NB6F19	R6	IO226PB7F21	G2	IO247PB7F23	K6
IO205PB6F19	T6	IO227NB7F21	H3	IO248NB7F23	D2
IO206NB6F19	W1	IO227PB7F21	H2	IO249NB7F23	G4
IO206PB6F19	Y1	IO229NB7F21	K2	IO249PB7F23	G3
IO207NB6F19	T2	IO229PB7F21	L2	IO251NB7F23	N10
IO207PB6F19	U2	IO230NB7F21	K1	IO251PB7F23	N9
IO208NB6F19	T1	IO230PB7F21	L1	IO253NB7F23	H4
IO208PB6F19	U1	IO231NB7F21	E2	IO253PB7F23	J4
IO209NB6F19	AA2	IO231PB7F21	F2	IO255NB7F23	J6
IO209PB6F19	AB2	IO232NB7F21	F1	IO255PB7F23	J5
IO210NB6F19	P5	IO232PB7F21	G1	IO257NB7F23	H5
IO211NB6F19	M1	IO233NB7F21	L3	IO257PB7F23	H6
IO211PB6F19	N1	IO233PB7F21	M3	Dedicated I/O	
IO212NB6F19	P1	IO234NB7F21	D1	GND	K5
IO212PB6F19	R1	IO234PB7F21	E1	GND	A18
IO213NB6F19	R8	IO235NB7F21	K4	GND	A2
IO213PB6F19	T8	IO235PB7F21	L4	GND	A24
IO215NB6F20	U4	IO236NB7F22	M6	GND	A25

Revision	Changes	Page
Revision 12 (v2.4)	Revised ordering information and timing data to reflect phase out of –3 speed grade options.	
	Table 2-3 was updated.	2
Revision 11 (v2.3)	The "Packaging Data" section is new.	iv
	Table 2-2 was updated.	2-1
	"VCCDA Supply Voltage" was updated.	2-9
	"PRA/B/C/D Probe A, B, C and D" was updated.	2-10
	The "User I/Os" was updated.	2-11
Revision 10 (v2.2)	Figure 1-3 was updated.	1-2
	Table 2-2 was updated.	2-1
	The "Power-Up/Down Sequence" section was updated.	2-1
	Table 2-4 was updated.	2-3
	Table 2-5 was updated.	2-4
	The "Timing Characteristics" section was added.	2-7
	Table 2-7 was updated.	2-7
	Figure 2-1 was updated.	2-8
	The External Setup and Clock-to-Out (Pad-to-Pad) equations in the "Hardwired Clock – Using LVTTTL 24 mA High Slew Clock I/O" section were updated.	2-8
	The External Setup and Clock-to-Out (Pad-to-Pad) in the "Routed Clock – Using LVTTTL 24 mA High Slew Clock I/O" section were updated.	2-8
	The "Global Pins" section was updated.	2-10
	The "User I/Os" section was updated.	2-11
	Table 2-17 was updated.	2-19
	Figure 2-8 was updated.	2-20
	Figure 2-13 and Figure 2-14 were updated.	2-24
	The following timing parameters were renamed in I/O timing characteristic tables from Table 2-22 to Table 2-60: $t_{IOCLKQ} > t_{CLKQ}$ $t_{IOCLKY} > t_{OCLKQ}$	2-26 to 2-52
	Timing numbers were updated from Table 2-22 to Table 2-78.	2-26 to 2-69
	The "R-Cell" section was updated.	2-58
	Figure 2-59 was updated.	2-89
	Figure 2-60 was updated.	2-89
	Figure 2-67 was updated.	2-100
	Figure 2-68 was updated.	2-101
	Table 2-89 to Table 2-93 were updated.	2-90 to 2-94
	Table 2-98 to Table 2-102 were updated.	2-102 to 2-106